

System specification (1)

Productivity	UPH	Unit/hour	10,000 (Based on dry running)
Input	Wafer Size	inch	Max 8.0 inch Programmable Wafer Stretch (12mm max)
Output	Waffle/GEL Pack	Ea	2", 4" or custom per spec.
System Reliability	MTBA	hours	2
	MTBF	hours	168
	MTTA	minutes	Max. 3
	MTTR	minutes	Max. 30

System specification (2)

Die Placement Accuracy	um	+/-25um
Die Rotation Accuracy	°	+/- 1°
Minimum applicable die size	mm	.5 x .5
Maximum applicable die size	mm	10 x 10
Vision	-	2 CAMERAS (DISPENSING, WAFER, BONDING STAGE)
Dimension	mm	700mm X 1,100mm X 1,500mm (Without LOADER/UNLOADER) 1,400mm X 1,100mm X 1,500mm (With LOADER/UNLOADER)
Wafer Mapping	Optional	Compatible with ALPS (Kinesys) - Optional